

CMOS BCD-to-Seven-Segment Latch/Decoder/Driver For Liquid-Crystal Displays

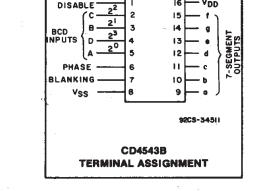
High-Voltage Types (20-Volt Rating)

Features:

- Display blanking of all illegal input combinations
- Latch storage of code
- Capability of driving two low power TTL loads, two HTL loads, or one low power Schottky load over the full rated-temperature range
- Pin-for-pin replacement for the CD4056B (with pin 7 tied to V_{SS})
- Direct LED driving capability

■ CD4543B is a BCD-to-seven segment latch/decoder/driver designed primarily for liquid-crystal display (LCD) applications. It is also capable of driving light emitting diode (LED), incandescent, gas-discharge, and fluorescent displays. This device is functionally similar to and serves as direct replacement for the CD4056B when pin 7 is connected to Vss. It differs from the CD4056B in that it has a display blanking capability instead of a level-shifting function and requires only one power supply. When the CD4056B is used in the level shifting mode, two power supplies are required. When the CD4543B is used for LCD applications, a square wave must be applied to the PHASE input and the backplane of the LCD device. For LED applications a logic 0 is required at the PHASE input for common-cathode devices; a logic 1 is required for commonanode devices (see truth table).

The CD4543B is supplied in 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).



- 100% tested for quiescent current at 20 V
- Maximum input current of 1 µA at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
- Noise margin (full package-temperature range)= 1 V at V_{DD}=5 V 2 V at V_{DD}=10 V 2.5 V at V_{DD}=15 V
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

Applications:

- Instrument display driver
- Dashboard display driver
- Computer/calculator display driver
- Timing device driver (clocks, watches, timers)

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (V _{DD})	
Voltages referenced to VSS Terminal)	,0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS	0.5V to V _{DD} +0.5V
DC INPUT CURRENT, ANY ONE INPUT	
POWER DISSIPATION PER PACKAGE (PD):	
For TA = -55°C to +100°C	500mW
For T _A = +100°C to +125°C	Derate Linearity at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR	
FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)	
OPERATING-TEMPERATURE RANGE (TA)	55°C to +125°C
STORAGE TEMPERATURE RANGE (Tstg)	65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):	
At distance $1/16 \pm 1/32$ inch $(1.59 \pm 0.79$ mm) from case for 10s max	+265°C

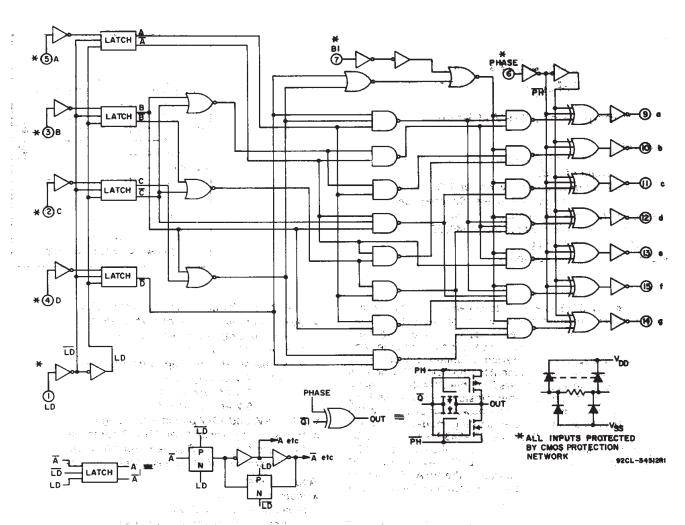


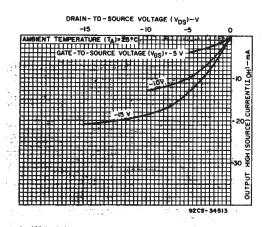
Fig. 1 - BCD-to-seven-segment latch/decoder/driver CD4543B logic circuit diagram.

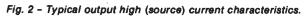
RECOMMENDED OPERATING CONDITIONS at TA=25°C, Unless Otherwise Specified
For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

		Lin			
CHARACTERISTIC	V _{DD} (V)	MIN.	TYP.	UNITS	
Supply-Voltage Range (For TA=Full Package-Temperature Range)		3	- 18	٧	
	5	250	125		
Latch Disable Pulse Width twh	10	100	50		
	15	80	40	1	
	5	60	15		
Minimum Data Setup Time tsu	10	20	-5	ns	
	15	10	-5	_	
	5	25	-5]	
Minimum Data Hold Time t _H	10	20	10	1	
	15	20	10		

STATIC ELECTRICAL CHARACTERISTICS

CUADAG	error and enter some some some some some some some som	СО	NDITION	IS	Lin	C)						
CHARAC-		٧o	VIN	V _{DD}			Τ	1	1	+25		UNITS
		(V)	(V)	(V)	-55	-40	+85	+125	Min.	Typ.	Max.)
Quiescent		-	0, 5	5	5	5	150	150	_	0.04	5	;
Device	1. mg	<u></u>	0,10	.10	10	10	300	300		0.04	10	
Current	IDD	12.1	0,15	15	20	20	600	600		0.04	20	μΑ
Max.			0,20	20	100	100	3000	3000	_	0.08	100	
Output Low (Sink)		0.4	0, 5	5	0.64	0.61	0.42	0.36	0.51	1	_	
Current	1	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6		į į
Min.	IOL	1:.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8		
Output High		4.6	0, 5	. 5	-0.46	-0.44	-0.30	-0.26	-0.37	-0.75	111-11	mA
(Source)		2.5	0, 5	5	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6		
Current	IOH"	9.5	0,10	10	-0.98	-0.92	-0.68	-0.55	-0.8	-1.6	<u> </u>	
Min.		13.5	0,15,	15	-3.33	-3.18	-2.2	-1.9	-2.7	-5.4 °		
Output Voltage:	i i i i i i i i i i i i i i i i i i i	1	0, 5	5		0.0	05			0	0.05	
Low-Level	VOL		0,10	10		0.05				0	0.05	
Max.		-	0,15	15		0.6	05			0	0.05	
Output Voltage:		1	0, 5	5		4.	95		4.95	5		, V ,
High-Level	Voн		0,10	10	191	9.	95	8	9.95	10	_	1 / Jan 19
Min.			0,15	15		14.	95		14.95	15		
Input Low		0.5,4.5	1	5		1.	5	;		_	1.5	
Voltage	٧١٢	1, 9	<u> 2 – </u>	10		3	3		_		3	
Max.		1.5,13.5	<u>, –</u>	15	1	4	<u>.</u>	1	_	_	4	
Input High		0.5,4.5	. —	5		3.	5		3.5	_	_	٧
Voltage	VIН	1, 9		10		7			7		_	
Min.		1.5,13.5	<i>–</i>	15		11				_	_	
Input Current Max.	ΙΝ	_	0,18	18	±0.1	±0.1	±1	±1	<u>(</u> ™)	±10 ⁻⁵	±0.1	μΑ





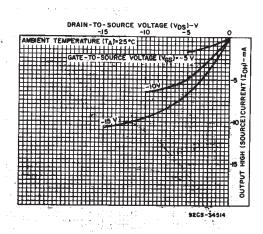


Fig. 3 - Minimum output high (source) current characteristics.

DYNAMIC ELECTRICAL CHARACTERISTICS at TA=25°C; CL=50 pF, input tr,tf=20 ns, RL=200 kΩ

CHARACTERIST	IC	TEST CONDITIONS		LIMITS All Package	•	UNITS
		V _{DD} (V)	MIN.	TYP.	MAX.	
Propagation Delay Time	tPHL	5	_	600	1200	
		10	-	200	400	
		15	_	150	300	
		5	_	500	1000	
	^t PLH	10	-	200	400	
		15		150	300	
		5		180	360	
Transition Time	THL	10	-	90	180	
	1	15	· -	65	130	
		5	[180	360	ns
	tTLH	10		90	180	
		15		65	130	
		5	250	125	_	
Latch Disable Pulse Width	twH	- 10	100	50		
		15	80	40		
		5	60	15		
Address Setup Time	tsu	10	20	-5		
		15	10	5		
		5	25	-5	_	
Address Hold Time	tн	10	20	10	-	
	<u> </u>	15	20	10		
Input Capacitance	CIN	Any Input	_	5	7.5	pF

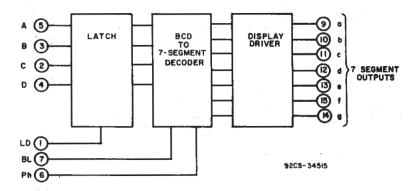


Fig. 4 - BCD-to-seven-segment latch/decoder/driver functional diagram.

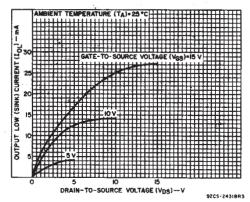


Fig. 5 - Typical output low (sink) current characteristics.

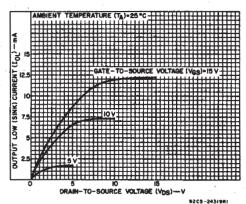


Fig. 6 - Minimum output low (sink) current characteristics.

TRUTH TABLE FOR CD4543B

		INP	UT CC	DE		\$ 1 *2			OUT	PUT 8	TATE			
LD	ВІ	Ph*	D	С	В	, A	. a	b	С	d	•	f	9	DISPLAY
х	1	0	x	x	X	X	0	O	0	0	0	0	0	CHAR- ACTER
1	0	0	0	0	0	0	1	1	1	1	1	1	0	
1	l .			_		Table Tabl			l '			· ·		1
1	0	0	0	0	0 '	1	0	1	1	0	0	0	0	
1	0	0	0	0	1	0	1	1	0	_1	1	0	1	E E
1	0	0	0	0	1	1	. 1	1.	1	1	0	0	1	;= <u> </u>
1	0	0	0	γ :1 4	0	0	0 .	1	. sy 1 sy s	. 0	0,	√ 1	1	Ц
1	0	0	0	1	0	1	1	0	1	1	0	1	1	5
1	0	0	0	1	1	0	1	. 0	1	1	1	1	10	5
1	0	0	0	1	1	1	1	1	1	0	0	0	0	
1	0	0	1	0	0	0	1	11	1	1	1	1	1	H
, 1 m	.0	0	1	0	0	1	1.	1	1	1	0	1	1	i i
1,33	0	0	1	0	1	0	0	0	0	. 0	0	0	0	Blank
1	0	0	1	0	1	1	0	0	0	0	0	0	0	Blank
1-	0	O	1	1	0	- 0	0	0	0	0	0	0	0	Blank
1	0	o	1	1 1	0	1	0	0	0	0	o	0	0	Blank
1	0	0	1	1	1	ا ہ ا	0	0	0	0	0	o	0	Blank
1	0	0	1 1	1	1	1	0	0	0	0	0	0	0	Blank
0	0	.0	X	X	X	X				: **	-	<u> </u>		asa in the gas
†	†	1		. <u> </u>	†		Inverse of Output Combinations Above							Display as above

X=Don't care.

^{**=}Depends upon the BCD code previously applied when LD=1.

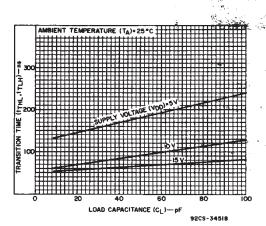


Fig. 7 - Typical transition time as a function of load capacitance.

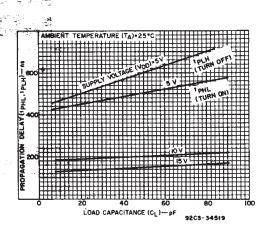


Fig. 8 - Typical propagation delay time as a function of load capacitance.

^{†=}Above combinations.

^{*=}For liquid-crystal readouts, apply a square wave to Ph.
For common cathode LED readouts, select Ph=0.
For common anode LED readouts, select Ph=1.

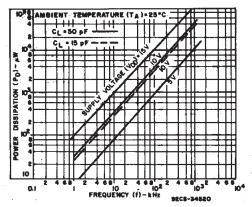


Fig. 9 - Typical dynamic power dissipation as a function of frequency.

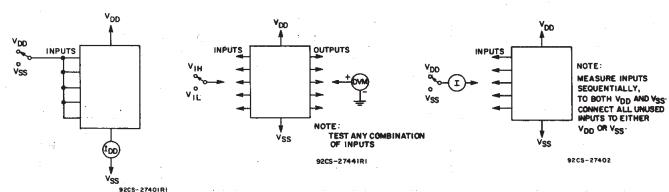
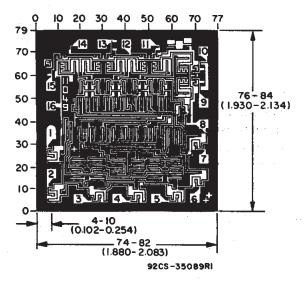


Fig. 10 - Quiescent device current test circuit.

Fig. 11 - Input voltage test circuit.

Fig. 12 - Input current test circuit.



Dimensions and pad layout for CD4543BH.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10⁻³ inch).





11-Apr-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
CD4543BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD4543BE	Samples
CD4543BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD4543BE	Samples
CD4543BM	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4543BM	Samples
CD4543BM96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4543BM	Samples
CD4543BM96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4543BM	Samples
CD4543BM96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4543BM	Samples
CD4543BME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4543BM	Samples
CD4543BMG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4543BM	Samples
CD4543BMT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4543BM	Samples
CD4543BMTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4543BM	Samples
CD4543BMTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4543BM	Samples
CD4543BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4543B	Samples
CD4543BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4543B	Samples
CD4543BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4543B	Samples
CD4543BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM543B	Samples
CD4543BPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM543B	Samples
CD4543BPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM543B	Samples



PACKAGE OPTION ADDENDUM

11-Apr-2013

Orderable Device		Package Type	Package Drawing	Pins	Package Qty		Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
CD4543BPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM543B	Samples
CD4543BPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM543B	Samples
CD4543BPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM543B	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4543BM96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD4543BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4543BPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4543BM96	SOIC	D	16	2500	333.2	345.9	28.6
CD4543BNSR	SO	NS	16	2000	367.0	367.0	38.0
CD4543BPWR	TSSOP	PW	16	2000	367.0	367.0	35.0

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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